



A) DEVICE-,DRAWING NUMBER:

B) ASSEMBLY CODE: BEZ-X

C) SCALE: 15 / 1

D) DIE SIZE:

E) DIE ATTACH PAD SIZE: 260 X 260 mil

F) PACKAGE TYPE/BODY SIZE: LQFP 64LD / (10x10x1.4mm)

G) BONDPAD PITCH (MIN):

H) BOND PAD SIZE (MIN):

I) WIRE SIZE:

J) WAFER THICKNESS:

K) CAVITY (UP OR DOWN): UP

L) REMARKS:

QA - APPROVAL:

REV.: